1 | Silicon

- · Integrated circuits changed computer circutries
- · Circuts's sillicon purified as polycillion chunks
 - · The cubic seed will form a new cubic sillicon
 - · Impurities added to sillicon to cause it to conduct
 - Negative charged free carrier (asinic) => n type
 - Positive charged carrier (boron) => p type
- · Christle ground to form ingots
- · Then, sliced thin as wafers
- · Wafers are then ground thin + removed of surface contaminates
- · Then, wafers are checked for resistivity
- CMOS
 - · n-type transitior sandwich a p type region
 - A charge on the gate wolud cause the charge to go through from source => drain
 - · Vise, versa
- · Meaning, when the P-N circut combinations are on, the N-P combination is off
- High temperature used to grow sillicon dioxide to protect the sillicon as sillicon interacts with pure exygen
- · Photoresist smeared on the wafer, and light is exposed to each part to etch patters
- · Then, lazers/plasma/acid guides etching of the wafer suface
- · Plasma implimant impurities to cause conductivity
- · Photoresist then washed off
- · The wafer is then cleaned off

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